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08-23-2007

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U.S. DEPARTMENT OF COMMERCE
United States Patent and Trademark Office

8.16.07

To the Director of the U.S. Patent [illegible] record the attached documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):

Kazutoshi SHIMIZUME,
Takaaki YAMADA

Execution Date(s) 08/10/2007, 08/13/2007

Additional name(s) of conveying party(ies) attached? ☐ Yes ☑ No

2. Name and address of receiving party(ies)

Name: Sony Corporation

Internal Address:

Street Address: 1-7-1 Konan

Minato-ku, Tokyo, Japan

City:

State:

Country: Zip:

Additional name(s) & address(es) attached? ☐ Yes ☑ No

U.S. PTO 11893573 081607

3. Nature of conveyance:

☑ Assignment ☐ Merger

☐ Security Agreement ☐ Change of Name

☐ Government Interest Assignment

☐ Executive Order 9424, Confirmatory License

☐ Other

4. Application or patent number(s): ☑ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☑ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Robert J. Depke

Internal Address: ROCKEY, DEPKE & LYONS, LLC.

Street Address: 233 S. Wacker Dr.

Suite 5450

City: Chicago

State: IL Zip: 60606

Phone Number: 312-277-2006

Fax Number: 312-704-8137

Email Address: rdepke@rdlklaw.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) $ 40.00

☐ Authorized to be charged by credit card

☐ Authorized to be charged to deposit account

☑ Enclosed

☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers
Expiration Date

b. Deposit Account Number

Authorized User Name

9. Signature:

Signature

8/16/07
Date

Robert J. Depke
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 5

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

08/22/2007 DBYRNE 00000041 11893573

01 FC:8021 40.00 OP

S07P1156US00
075834.01040
Docket Number: ____________

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (i only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in SEMICONDUCTOR DEVICE, SEMICONDUCTOR INTEGRATED CIRCUIT AND BUMP RESISTANCE MEASUREMENT METHOD for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be grantec therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, b hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: ____________________, Filing Date: ____________________.

This assignment executed on the dates indicated below.

Kazutoshi SHIMIZUME
Name of first or sole inventor
Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of first or sole inventor

August 10, 2007
Signature of first or sole inventor
Date of this assignment

Takaaki YAMADA

Name of second inventor Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Signature of second inventor Date of this assignment

Name of third inventor Execution date of U.S. Patent Application

Residence of third inventor

Signature of third inventor Date of this assignment

Name of fourth inventor Execution date of U.S. Patent Application

Residence of fourth inventor

Signature of fourth inventor Date of this assignment

Name of fifth inventor Execution date of U.S. Patent Application

Residence of fifth inventor

Signature of fifth inventor Date of this assignment

S07P1156US00
075834.01040
Docket Number: ____________

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in SEMICONDUCTOR DEVICE, SEMICONDUCTOR INTEGRATED CIRCUIT AND BUMP RESISTANCE MEASUREMENT METHOD for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficienc of which are hereb acknowledged, I, as a sole or joint inventor as indicated below, b hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: ____________, Filing Date: ____________.

This assignment executed on the dates indicated below.

Kazutoshi SHIMIZUME
Name of first or sole inventor — Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of first or sole inventor

Signature of first or sole inventor — Date of this assignment

Takaaki YAMADA

Name of second inventor Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Takaaki Yamada August 13, 2007

Signature of second inventor Date of this assignment

Name of third inventor Execution date of U.S. Patent Application

Residence of third inventor

Signature of third inventor Date of this assignment

Name of fourth inventor Execution date of U.S. Patent Application

Residence of fourth inventor

Signature of fourth inventor Date of this assignment

Name of fifth inventor Execution date of U.S. Patent Application

Residence of fifth inventor

Signature of fifth inventor Date of this assignment